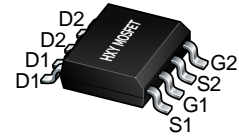




## Description

The AO4612 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



SOP-8

## General Features

$V_{DS} = 60V$   $I_D = 8.5A$

$R_{DS(ON)} < 48m\Omega @ V_{GS}=10V$

$V_{DS} = -60V$   $I_D = -7.7A$

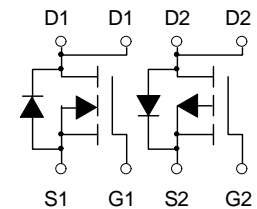
$R_{DS(ON)} < 85 m\Omega @ V_{GS}=-10V$

## Application

Wireless charging

Boost driver

Brushless motor



N-Channel and P-Channel

## Package Marking and Ordering Information

| Product ID | Pack  | Marking | Qty(PCS) |
|------------|-------|---------|----------|
| AO4612     | SOP-8 | 4612XXX | 3000     |

## Absolute Maximum Ratings ( $T_C=25^\circ C$ unless otherwise noted)

| Symbol                 | Parameter  | Rating     |            | Units        |
|------------------------|--|------------|------------|--------------|
|                        |  | N-Channel  | P-Channel  |              |
| VDS                    | Drain-Source Voltage                             | 60         | -60        | V            |
| VGS                    | Gate-Source Voltage                              | $\pm 20$   | $\pm 20$   | V            |
| $I_D @ T_A=25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$       | 8.5        | -7.7       | A            |
| $I_D @ T_A=70^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$       | 4.0        | -3         | A            |
| IDM                    | Pulsed Drain Current <sup>2</sup>                | 20         | -14        | A            |
| EAS                    | Single Pulse Avalanche Energy <sup>3</sup>       | 22         | 28.8       | mJ           |
| IAS                    | Avalanche Current                                | 21         | -24        | A            |
| $P_D @ T_A=25^\circ C$ | Total Power Dissipation <sup>4</sup>             | 2          | 2          | W            |
| TSTG                   | Storage Temperature Range                        | -55 to 150 | -55 to 150 | $^\circ C$   |
| TJ                     | Operating Junction Temperature Range             | -55 to 150 | -55 to 150 | $^\circ C$   |
| $R_{\theta JA}$        | Thermal Resistance Junction-Ambient <sup>1</sup> | 85         |            | $^\circ C/W$ |
| $R_{\theta JC}$        | Thermal Resistance Junction-Case <sup>1</sup>    | 62.5       |            | $^\circ C/W$ |



**N-Channel Electrical Characteristics (T<sub>J</sub> =25 °C, unless otherwise noted)**

| Symbol          | Parameter                                      | Conditions  | Min. | Typ.  | Max. | Unit  |
|-----------------|--|---|------|-------|------|-------|
| BVDSS           | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA  | 60   | 65    | ---  | V     |
| ΔBVDSS/ΔTJ      | BV <sub>DSS</sub> Temperature Coefficient      | Reference to 25°C, I <sub>D</sub> =1mA  | ---  | 0.063 | ---  | V/°C  |
| RDS(ON)         | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =10V, I <sub>D</sub> =5A  | ---  | 35    | 48   | mΩ    |
|                 |  | V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A   | ---  | 41    | 65   |       |
| VGS(th)         | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA                                    | 1.2  | 1.75  | 2.5  | V     |
| ΔVGS(th)        | V <sub>GS(th)</sub> Temperature Coefficient    |   | ---  | -5.24 | ---  | mV/°C |
| IDSS            | Drain-Source Leakage Current                   | V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C                             | ---  | ---   | 1    | uA    |
|                 |  | V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C                             | ---  | ---   | 5    |       |
| IGSS            | Gate-Source Leakage Current                    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V  | ---  | ---   | ±100 | nA    |
| gfs             | Forward Transconductance                       | V <sub>DS</sub> =5V, I <sub>D</sub> =4A   | ---  | 28    | ---  | S     |
| Q <sub>g</sub>  | Total Gate Charge (4.5V)                       | V <sub>DS</sub> =48V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A                             | ---  | 19    | ---  | nC    |
| Q <sub>gs</sub> | Gate-Source Charge                             |   | ---  | 2.6   | ---  |       |
| Q <sub>gd</sub> | Gate-Drain Charge                              |   | ---  | 4.1   | ---  |       |
| Td(on)          | Turn-On Delay Time                             | V <sub>DD</sub> =30V, V <sub>GS</sub> =10V<br>, R <sub>G</sub> =3.3Ω,<br>I <sub>D</sub> =4A | ---  | 3     | ---  | ns    |
| T <sub>r</sub>  | Rise Time                                      |   | ---  | 34    | ---  |       |
| Td(off)         | Turn-Off Delay Time                            |   | ---  | 23    | ---  |       |
| T <sub>f</sub>  | Fall Time                                      |   | ---  | 6.0   | ---  |       |
| Ciss            | Input Capacitance                              | V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz   | ---  | 1027  | ---  | pF    |
| Coss            | Output Capacitance                             |   | ---  | 65    | ---  |       |
| Crss            | Reverse Transfer Capacitance                   |   | ---  | 45    | ---  |       |
| IS              | Continuous Source Current <sup>1,5</sup>       | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current   | ---  | ---   | 2.5  | A     |
| VSD             | Diode Forward Voltage <sup>2</sup>             | V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C                               | ---  | ---   | 1.2  | V     |

**Note :**

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation



**P-Channel Electrical Characteristics (T<sub>J</sub> =25 °C, unless otherwise noted)**

| Symbol                 | Parameter                                      | Conditions  | Min. | Typ.  | Max. | Unit |
|------------------------|--|---|------|-------|------|------|
| BVDSS                  | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA   | -60  | -65   | ---  | V    |
| ΔBVDSS/ΔT <sub>J</sub> | BV <sub>DSS</sub> Temperature Coefficient      | Reference to 25°C, I <sub>D</sub> =-1mA   | ---  | -0.03 | ---  | V/°C |
| RDS(ON)                | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =-10V, I <sub>D</sub> =-3A  | ---  | 72    | 85   | mΩ   |
|                        |  | V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A   | ---  | 100   | 105  |      |
| VGS(th)                | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA                               | -1.2 | 1.75  | -2.5 | V    |
| IDSS                   | Drain-Source Leakage Current                   | V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C                        | ---  | ---   | 1    | uA   |
|                        |  | V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C                        | ---  | ---   | 5    |      |
| IGSS                   | Gate-Source Leakage Current                    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V  | ---  | ---   | ±100 | nA   |
| gfs                    | Forward Transconductance                       | V <sub>DS</sub> =-5V, I <sub>D</sub> =-3A   | ---  | 8.5   | ---  | S    |
| Q <sub>g</sub>         | Total Gate Charge (-4.5V)                      | V <sub>DS</sub> =-48V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A                      | ---  | 12.1  | ---  | nC   |
| Q <sub>gs</sub>        | Gate-Source Charge                             |   | ---  | 2.2   | ---  |      |
| Q <sub>gd</sub>        | Gate-Drain Charge                              |   | ---  | 6.3   | ---  |      |
| Td(on)                 | Turn-On Delay Time                             | V <sub>DD</sub> =-15V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-1A | ---  | 9.2   | ---  | ns   |
| T <sub>r</sub>         | Rise Time                                      |   | ---  | 20.1  | ---  |      |
| Td(off)                | Turn-Off Delay Time                            |   | ---  | 46.7  | ---  |      |
| T <sub>f</sub>         | Fall Time                                      |   | ---  | 9.4   | ---  |      |
| Ciss                   | Input Capacitance                              | V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz                                      | ---  | 1137  | ---  | pF   |
| Coss                   | Output Capacitance                             |   | ---  | 76    | ---  |      |
| Crss                   | Reverse Transfer Capacitance                   |   | ---  | 50    | ---  |      |
| IS                     | Continuous Source Current <sup>1,5</sup>       | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current                                       | ---  | ---   | -2.5 | A    |
| VSD                    | Diode Forward Voltage <sup>2</sup>             | V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C                          | ---  | ---   | -1.2 | V    |

**Note :**

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.



### N-Channel Typical Characteristics

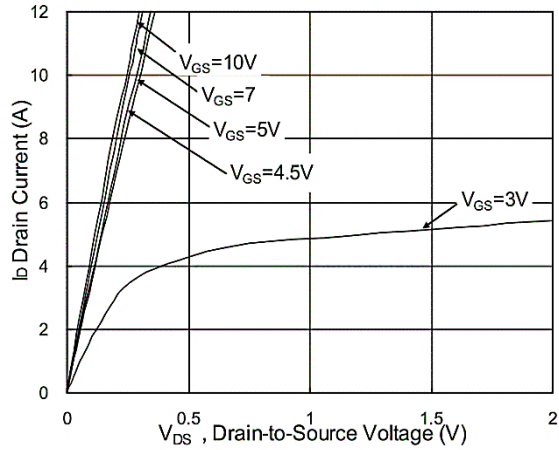


Fig.1 Typical Output Characteristics

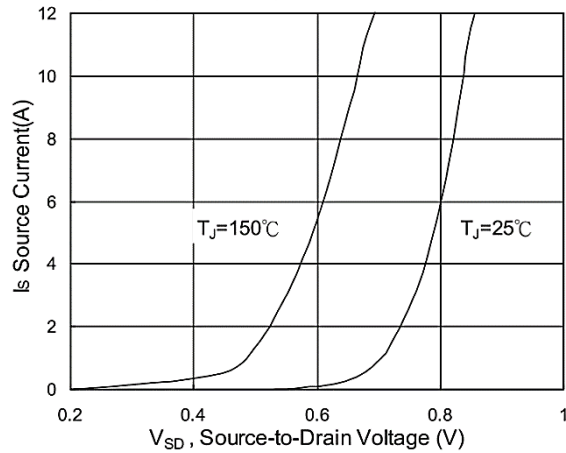


Fig.3 Source Drain Forward Characteristics

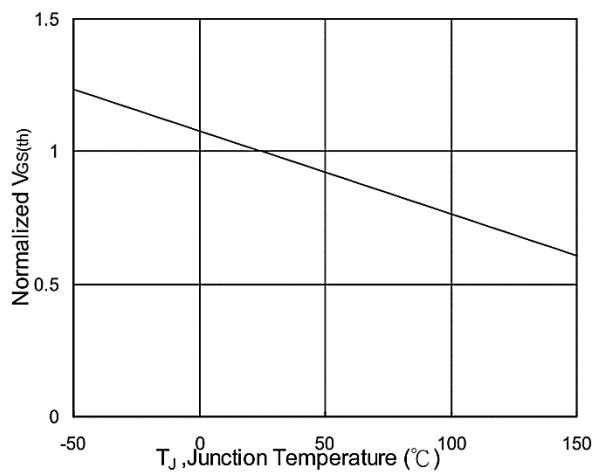


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

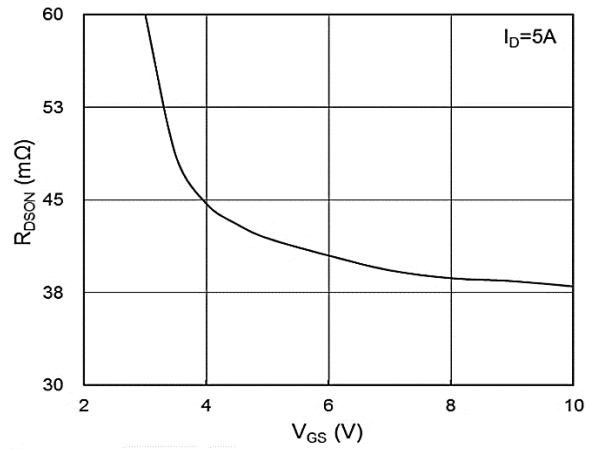


Fig.2 On-Resistance vs. G-S Voltage

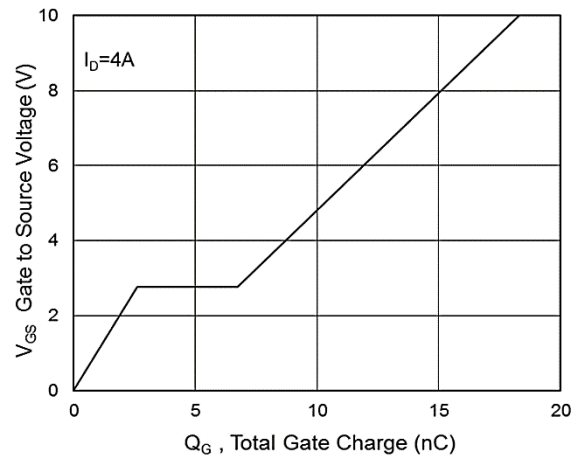


Fig.4 Gate-Charge Characteristics

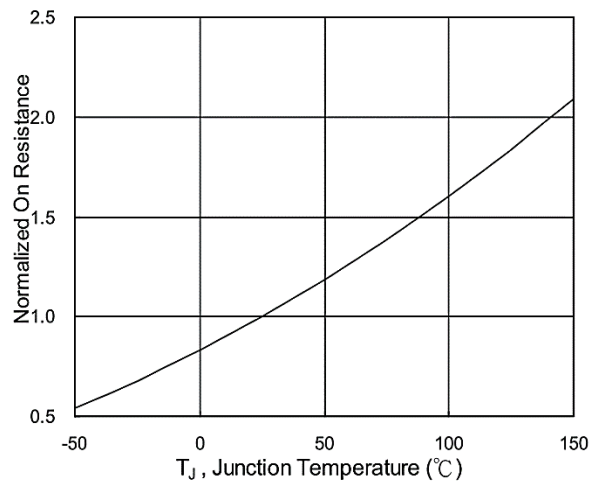


Fig.6 Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>



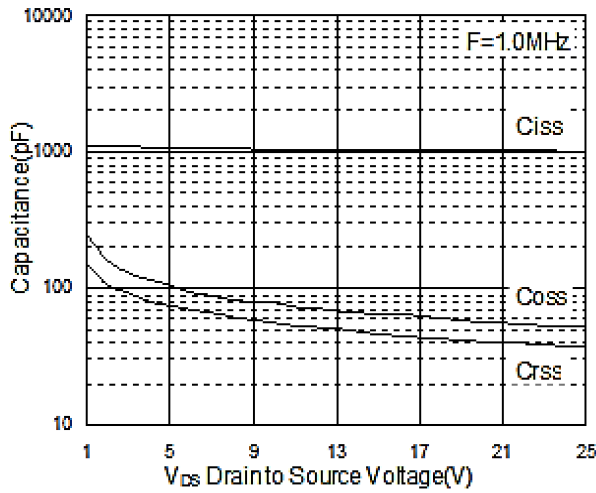


Fig.7 Capacitance

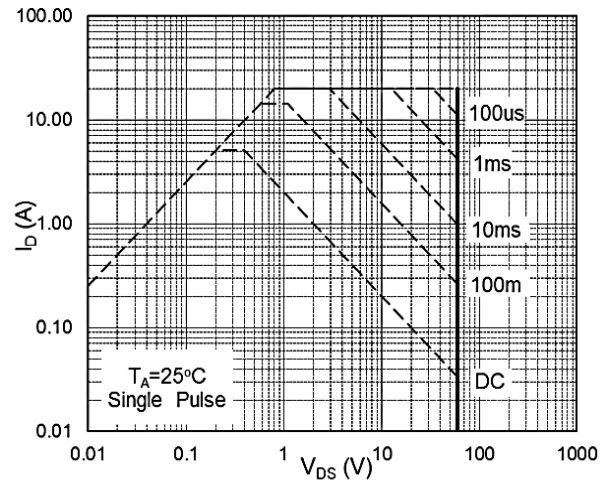


Fig.8 Safe Operating Area

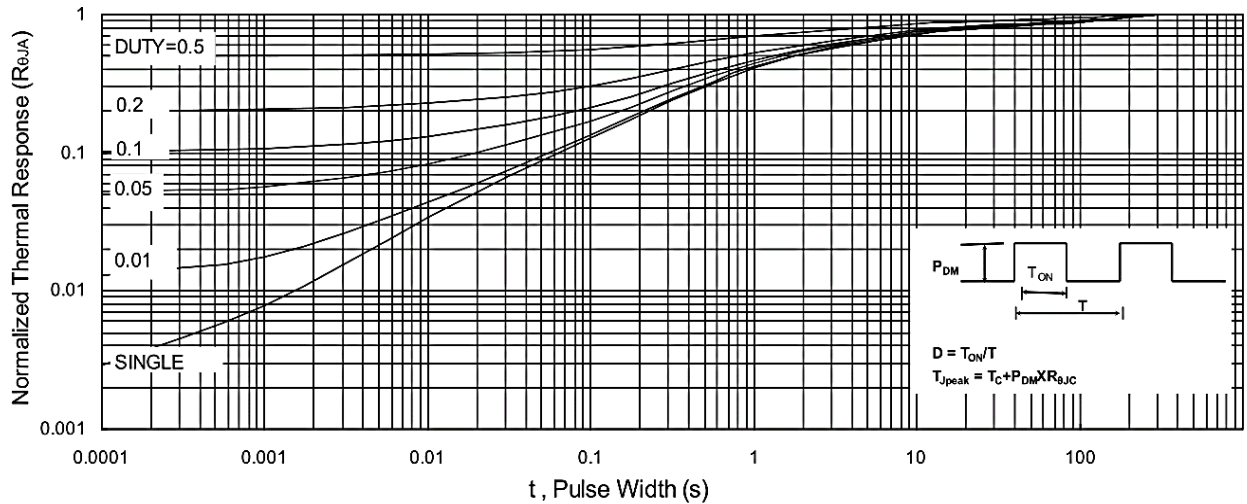


Fig.9 Normalized Maximum Transient Thermal Impedance

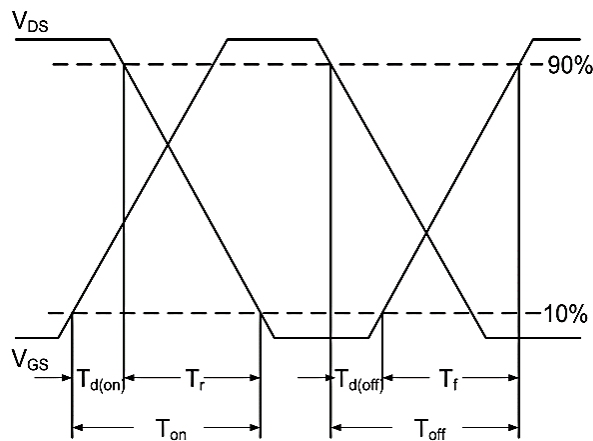


Fig.10 Switching Time Waveform

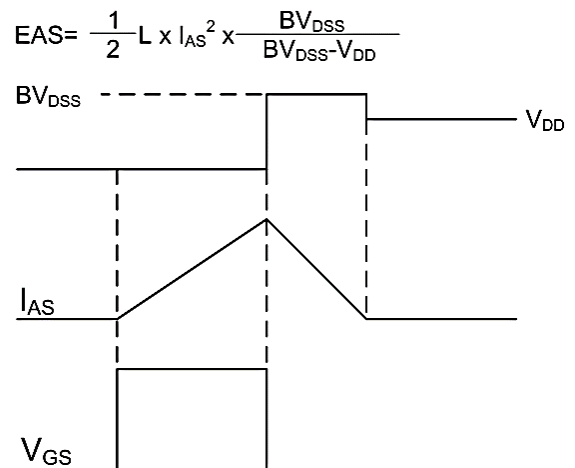


Fig.11 Unclamped Inductive Waveform



### P-Channel Typical Characteristics

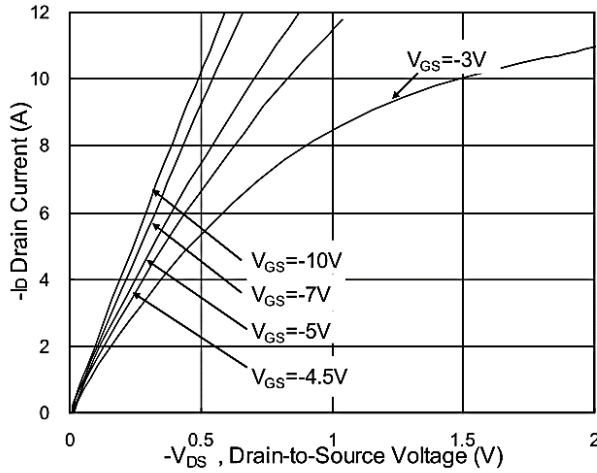


Fig.1 Typical Output Characteristics

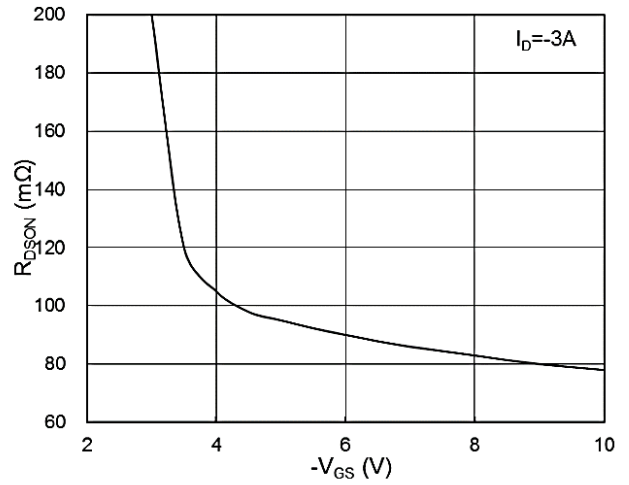


Fig.2 On-Resistance vs. G-S Voltage

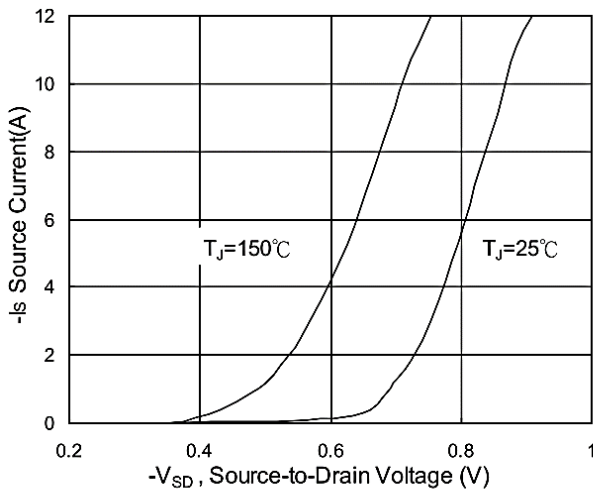


Fig.3 Source Drain Forward Characteristics

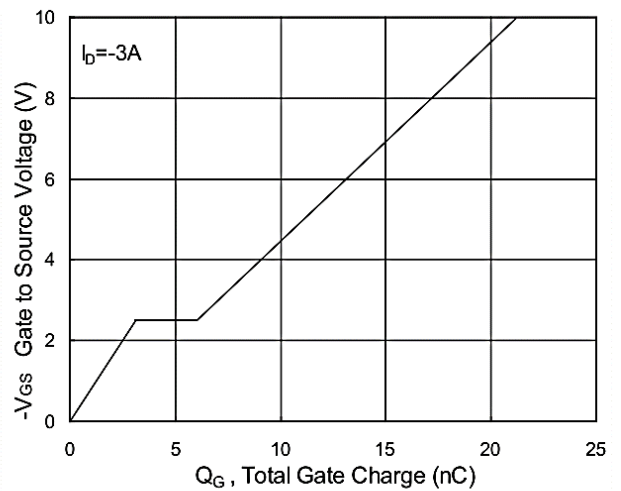


Fig.4 Gate-Charge Characteristics

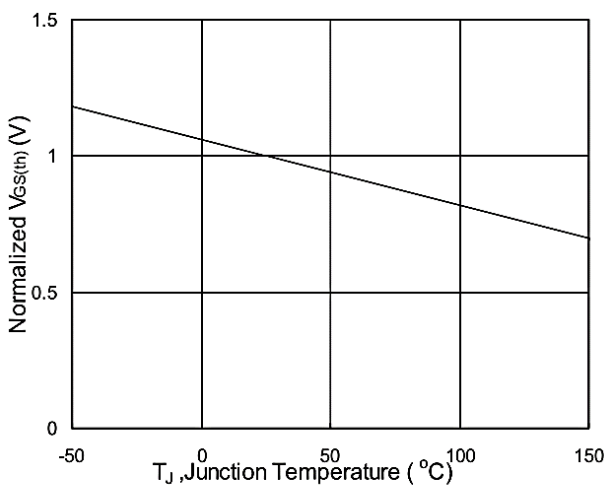


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

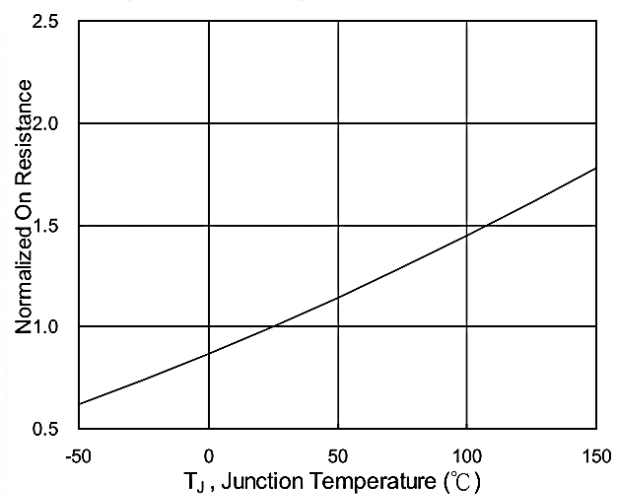


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

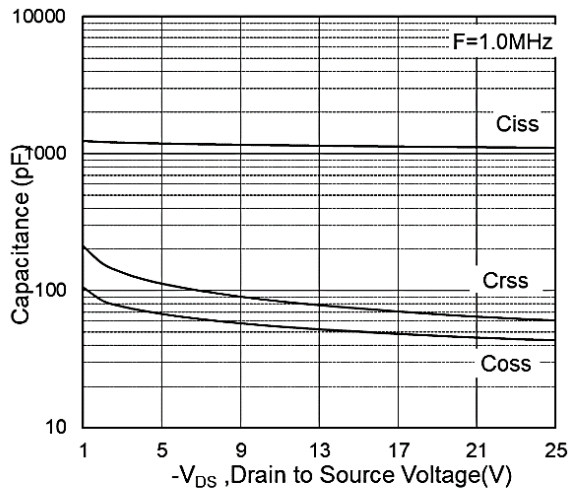


Fig.7 Capacitance

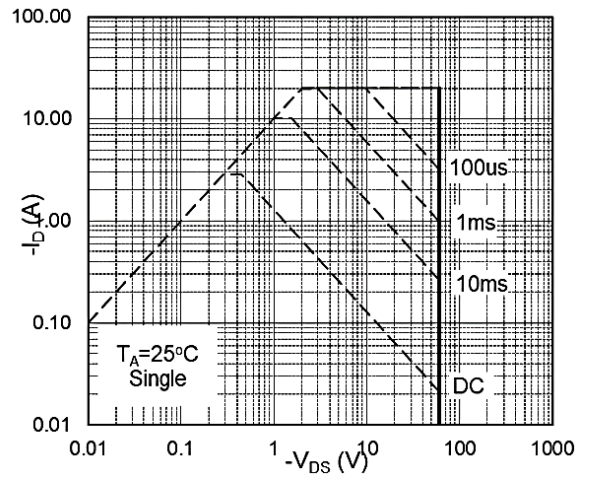


Fig.8 Safe Operating Area

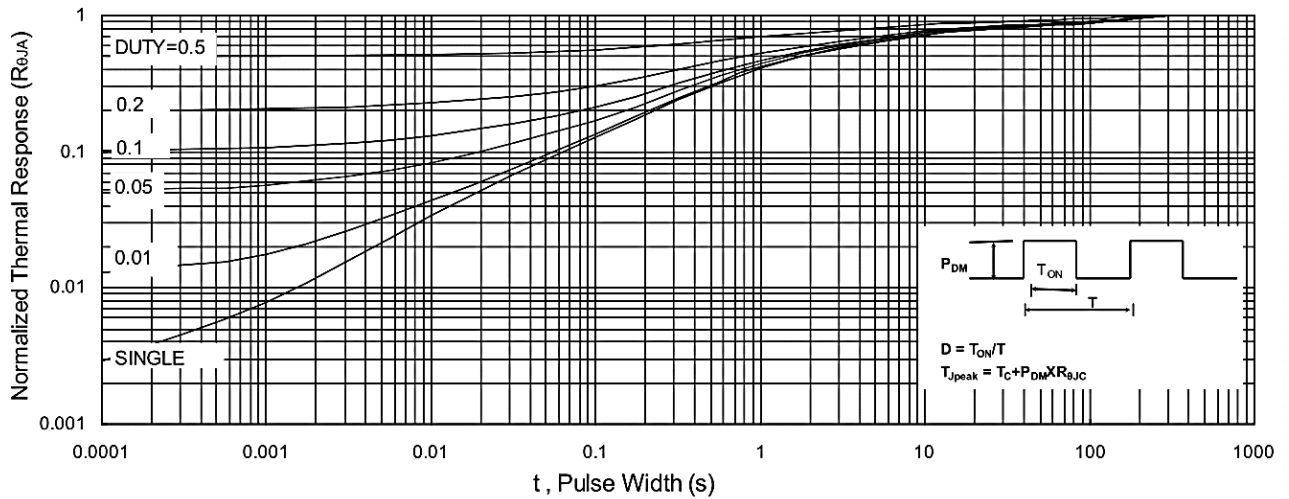


Fig.9 Normalized Maximum Transient Thermal Impedance

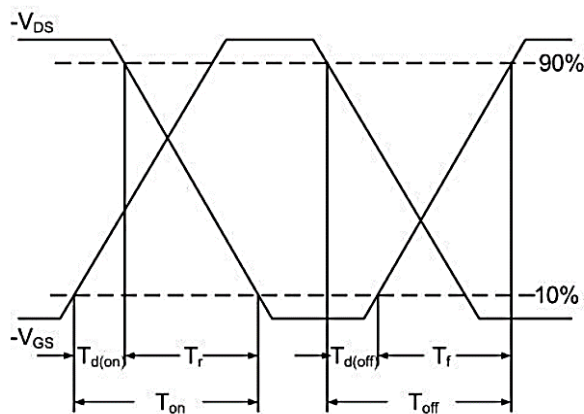


Fig.10 Switching Time Waveform

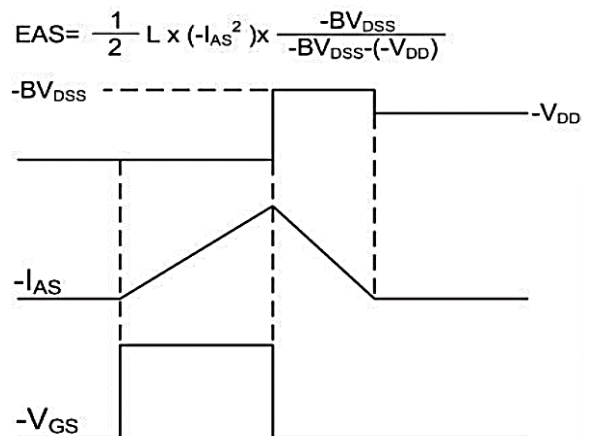
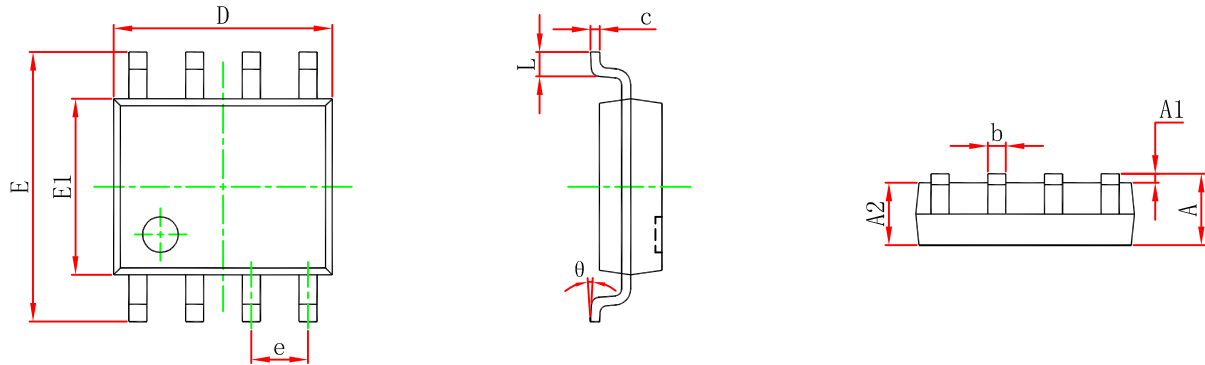


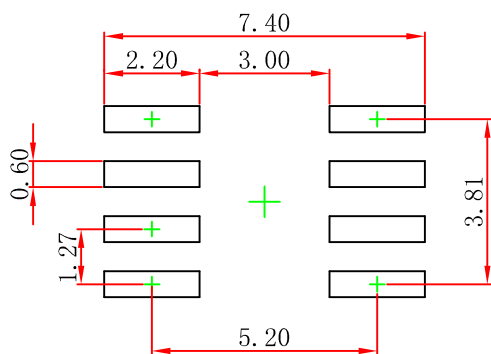
Fig.11 Unclamped Inductive Waveform



### SOP-8 Package Outline Dimensions



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.013                | 0.020 |
| c      | 0.170                     | 0.250 | 0.007                | 0.010 |
| D      | 4.800                     | 5.000 | 0.189                | 0.197 |
| e      | 1.270 (BSC)               |       | 0.050 (BSC)          |       |
| E      | 5.800                     | 6.200 | 0.228                | 0.244 |
| E1     | 3.800                     | 4.000 | 0.150                | 0.157 |
| L      | 0.400                     | 1.270 | 0.016                | 0.050 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$ .
  3. The pad layout is for reference purposes only.



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